

**AMENDMENTS TO THE SPECIFICATION:**

*Please replace the paragraph bridging Page 5, line 21 to Page 6, line 3, with the following:*

**DISCLOSURE SUMMARY OF THE INVENTION**

~~{Problems to be Solved by the Invention}~~

It is an object of the present invention to provide a one component resin composition curable with a combination of light and heat, which has excellent curability, especially in a light-shielded area.

*Please replace the paragraph bridging Page 6, line 21 to Page 7, line 6, with the following:*

~~{Means to solve the Problems}~~

The one component resin composition curable with a combination of light and heat according to the present invention is characterized in that it comprises (1) an epoxy resin, (2) an acrylic ester monomer and/or methacrylic ester monomer, or an oligomer thereof, (3) a latent epoxy curing agent, (4) a photo radical initiator, and (5) a compound having two or more thiol groups per molecule, wherein the ingredient (5) is contained in an amount of 0.001 to 5.0 parts by weight per 100 parts by weight of the resin composition.

*Please replace the paragraph bridging Page 8, line 21 to Page 9, line 11, with the following:*

~~{Effects of the Invention}~~

According to the invention, a one component resin composition curable with a combination of light and heat, which has excellent curability, especially in a light-shielded area, can be provided. Further, a liquid crystal sealant composition curable with a combination of light and heat, which is applicable to a one-drop-fill method having excellent characteristics of the cured product after light-curing and the stability of the cell gap after formation of a cell gap in the first step; and preventing the contamination of liquid crystal during heat-curing in the second step; and has excellent curability in a light-shielded area, as well as excellent adhesion reliability, especially, high-temperature and high-humidity adhesion reliability, can be further provided.

*Please replace the paragraph bridging Page 9, line 19 to Page 10, line 1, with the following:*

~~BEST MODE FOR CARRYING OUT~~ DETAILED DESCRIPTION OF THE  
INVENTION

Hereinafter, the one component resin composition curable with a combination of light and heat, and the liquid crystal sealant composition comprising the same will be explained in detail.

<One component resin composition curable with combination of light and heat>